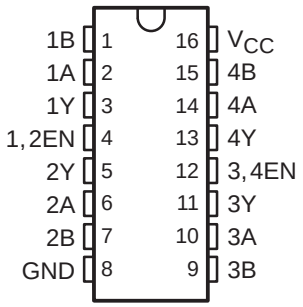
- **Meet or Exceed the Requirements of ANSI Standard EIA/TIA-422-B, RS-423-B, and RS-485**
- **Meet ITU Recommendations V.10, V.11, X.26, and X.27**
- **Designed for Multipoint Bus Transmission on Long Bus Lines in Noisy Environments**
- **3-State Outputs**
- **Common-Mode Input Voltage Range –12 V to 12 V**
- **Input Sensitivity . . . ±200 mV**
- **Input Hysteresis . . . 50 mV Typ**
- **High Input Impedance . . . 12 kΩ Min**
- **Operate From Single 5-V Supply**
- **Low-Power Requirements**
- **Plug-In Replacement for MC3486**

D OR N PACKAGE
(TOP VIEW)



description

The SN65175 and SN75175 are monolithic quadruple differential line receivers with 3-state outputs. They are designed to meet the requirements of ANSI Standards EIA/TIA-422-B, RS-423-B, and RS-485, and several ITU recommendations. These standards are for balanced multipoint bus transmission at rates up to 10 megabits per second. Each of the two pairs of receivers has a common active-high enable.

The receivers feature high input impedance, input hysteresis for increased noise immunity, and input sensitivity of ±200 mV over a common-mode input voltage range of ±12 V. The SN65175 and SN75175 are designed for optimum performance when used with the SN75172 or SN75174 quadruple differential line drivers.

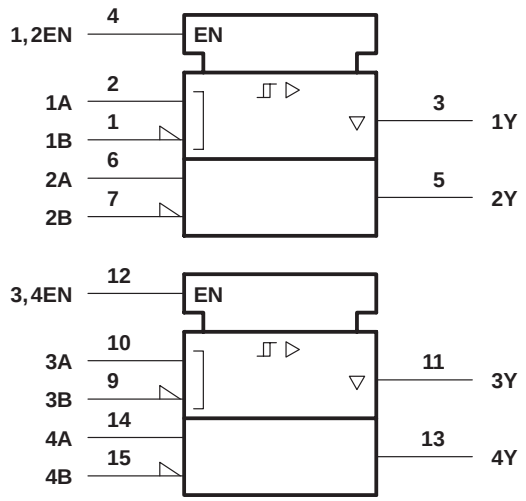
The SN65175 is characterized for operation from –40°C to 85°C. The SN75175 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE
(each receiver)

DIFFERENTIAL A – B	ENABLE	OUTPUT Y
$V_{ID} \geq 0.2$ V	H	H
-0.2 V $< V_{ID} < 0.2$ V	H	?
$V_{ID} \geq -0.2$ V	H	L
X	L	Z
Open circuit	H	?

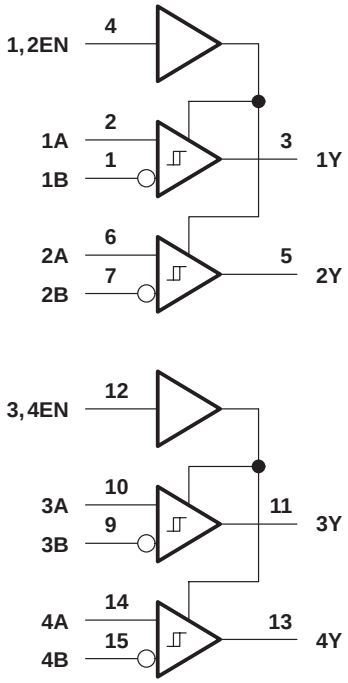
H = high level, L = low level, ? = indeterminate,
X = irrelevant, Z = high impedance (off)

logic symbol†

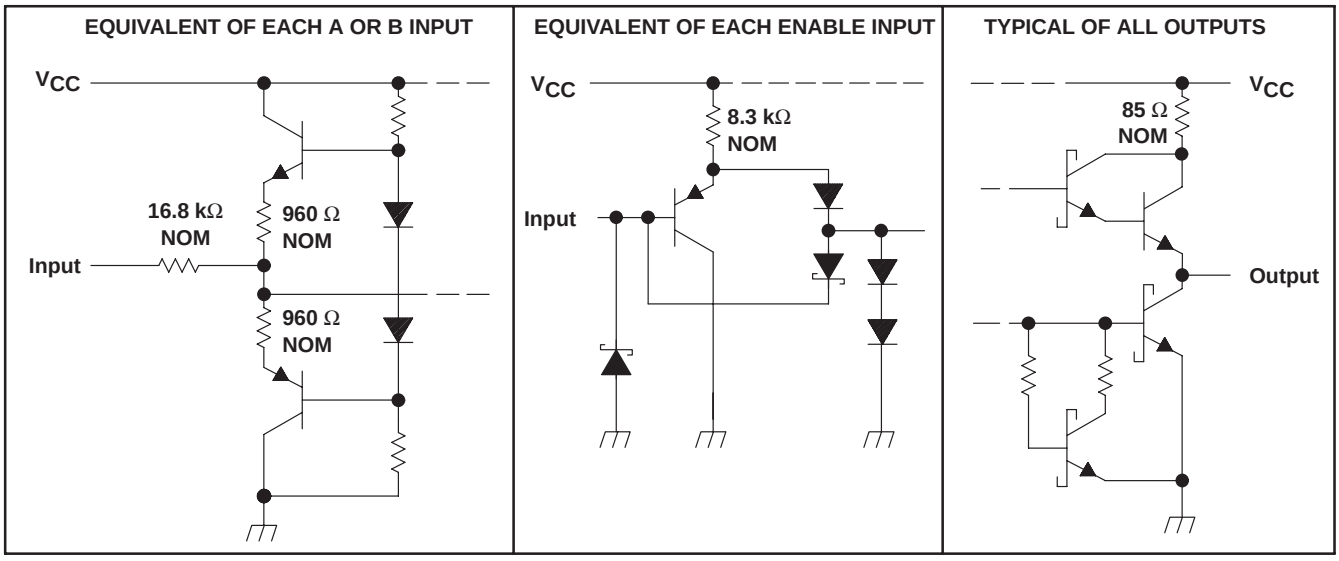


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage V_I, (A or B inputs) . . . . . ±25 V
Differential input voltage, V_{ID} (see Note 2) . . . . . ±25 V
Enable input voltage, V_I, EN . . . . . 7 V
Low-level output current, I_{OL} . . . . . 50 mA
Continuous total dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A: SN65175 . . . . . –40°C to 85°C
SN75175 . . . . . 0°C to 70°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential input voltage, are with respect to network ground terminal.
2. Differential-input voltage is measured at the noninverting input with respect to the corresponding inverting input.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING
D	950 mW	7.6 mW/°C	608 mW	494 mW
N	1150 mW	9.2 mW/°C	736 mW	598 mW

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
Common-mode input voltage, V_{IC}				±12	V
Differential input voltage, V_{ID}				±12	V
High-level enable-input voltage, V_{IH}		2			V
Low-level enable-input voltage, V_{IL}				0.8	V
High-level output current, I_{OH}				–400	μA
Low-level output current, I_{OL}				16	mA
Operating free-air temperature, T_A	SN65175	–40		85	°C
	SN75175	0		70	

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage and operating free-air temperature

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	V_O = 2.7 V,	I_O = –0.4 mA				0.2	V
$V_{IT–}$	Negative-going input threshold voltage	V_O = 0.5 V,	I_O = 16 mA		–0.2‡			V
V_{hys}	Hysteresis voltage ($V_{IT+} – V_{IT–}$)	See Figure 4				50		mV
V_{IK}	Enable-input clamp voltage	I_I = –18 mA					–1.5	V
V_{OH}	High-level output voltage	V_{ID} = 200 mV,	I_{OH} = –400 μA,	See Figure 1	2.7			V
V_{OL}	Low-level output voltage	V_{ID} = –200 mV,	See Figure 1	I_{OL} = 8 mA			0.45	V
				I_{OL} = 16 mA			0.5	
I_{OZ}	High-impedance-state output current	V_O = 0.4 V to 2.4 V					±20	μA
I_I	Line input current	Other input at 0 V,	See Note 3	V_I = 12 V			1	mA
				V_I = –7 V			–0.8	
I_{IH}	High-level enable-input current	V_{IH} = 2.7 V					20	μA
I_{IL}	Low-level enable-input current	V_{IL} = 0.4 V					–100	μA
r_i	Input resistance				12			kΩ
I_{OS}	Short-circuit output current§				–15		–85	mA
I_{CC}	Supply current	Outputs disabled					70	mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold voltage levels only.
§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.
NOTE 3: Refer to ANSI Standards EIA/TIA-422-B, RS-423-B, and RS-485 for exact conditions.

switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	See Figure 2		22	35	ns
t_{PHL}	Propagation delay time, high- to low-level output			25	35	ns
t_{PZH}	Output enable time to high level	See Figure 3		13	30	ns
t_{PZL}	Output enable time to low level			19	30	ns
t_{PHZ}	Output disable time from high level	See Figure 3		26	35	ns
t_{PLZ}	Output disable time from low level			25	35	ns

PARAMETER MEASUREMENT INFORMATION

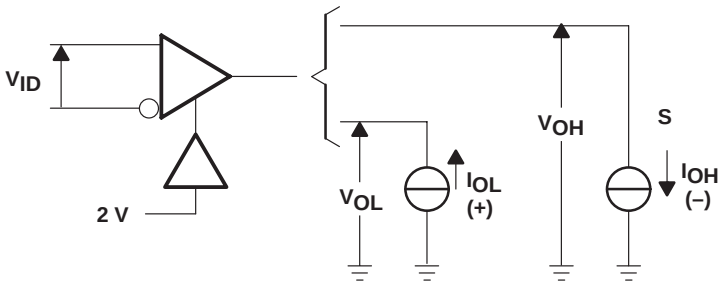
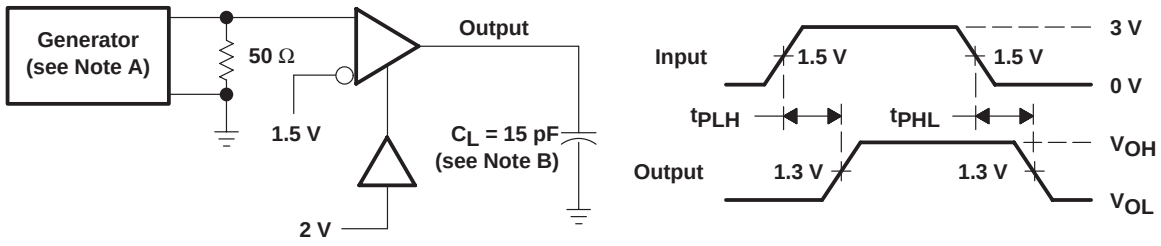


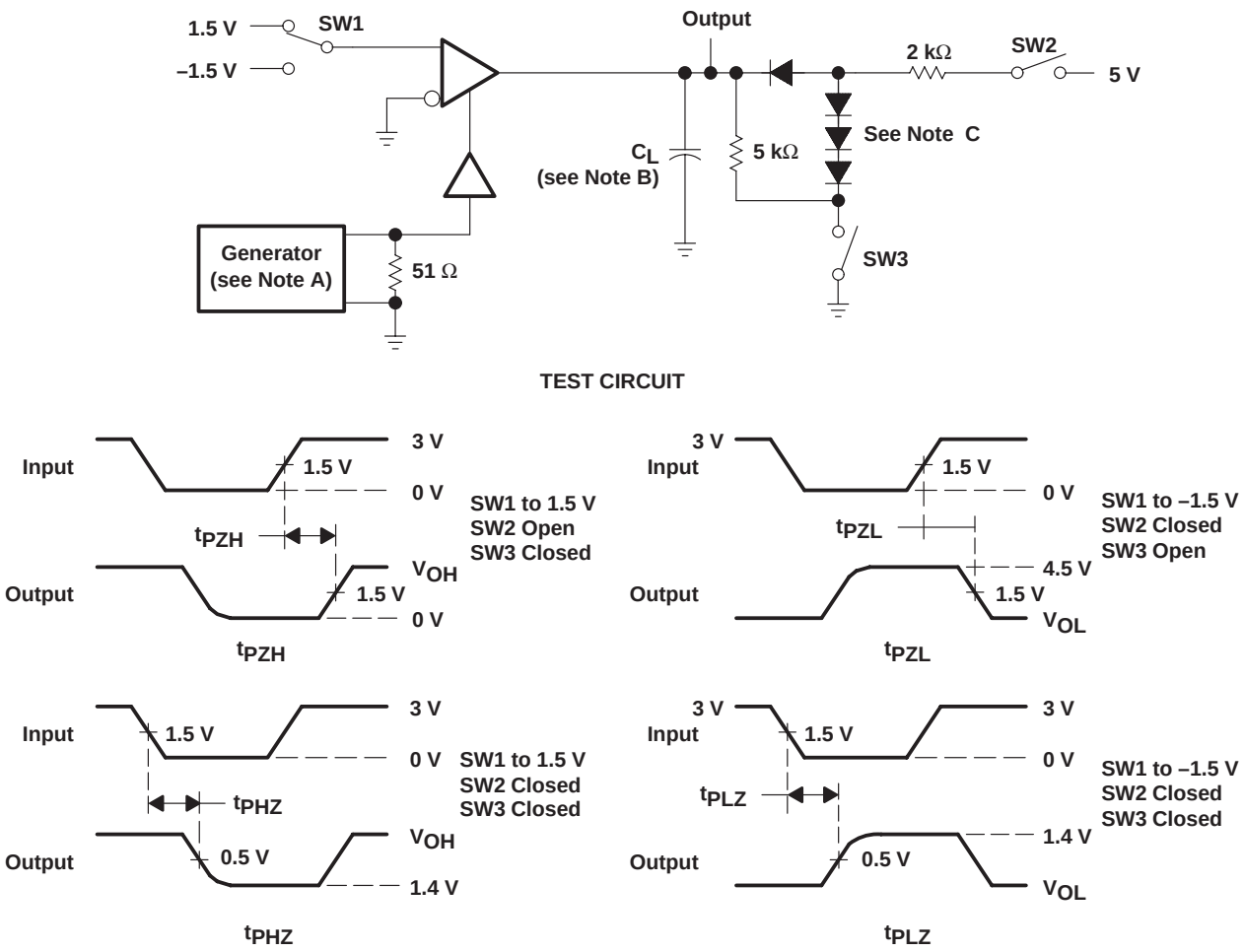
Figure 1. V_{OH}, V_{OL}



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, duty cycle = 50%, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and stray capacitance.

Figure 2. Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, duty cycle = 50%, $t_f \le 6$ ns, $t_r \le 6$ ns, $Z_O = 50\ \Omega$.
B. C_L includes probe and stray capacitance.
C. All diodes are 1N916 or equivalent.

Figure 3. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

OUTPUT VOLTAGE vs DIFFERENTIAL INPUT VOLTAGE

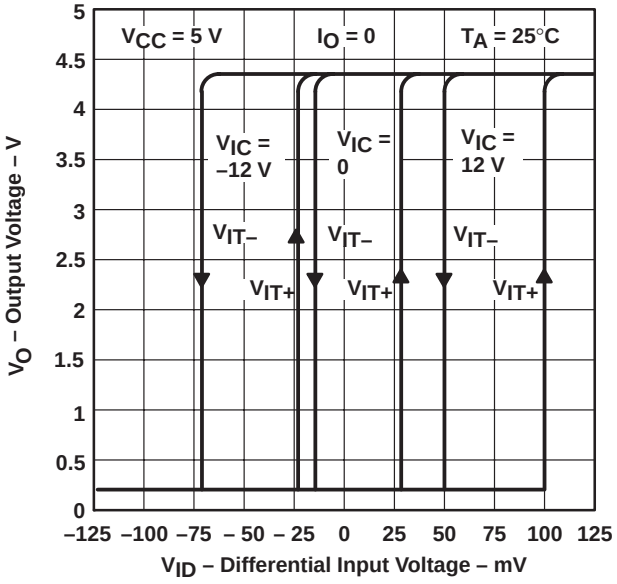


Figure 4

HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT

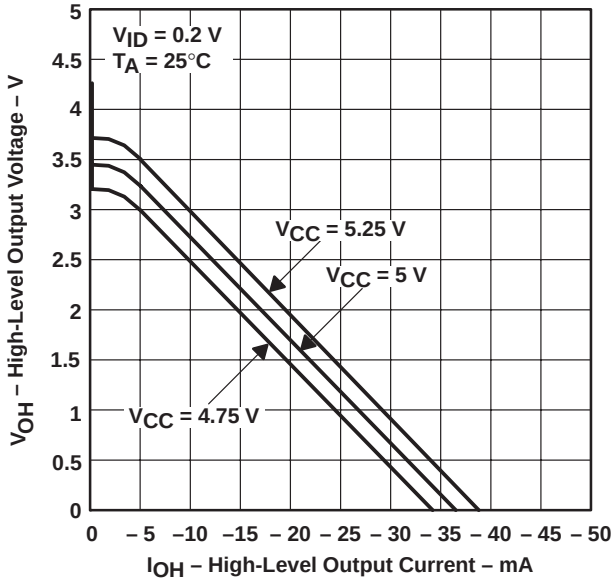


Figure 5

HIGH-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

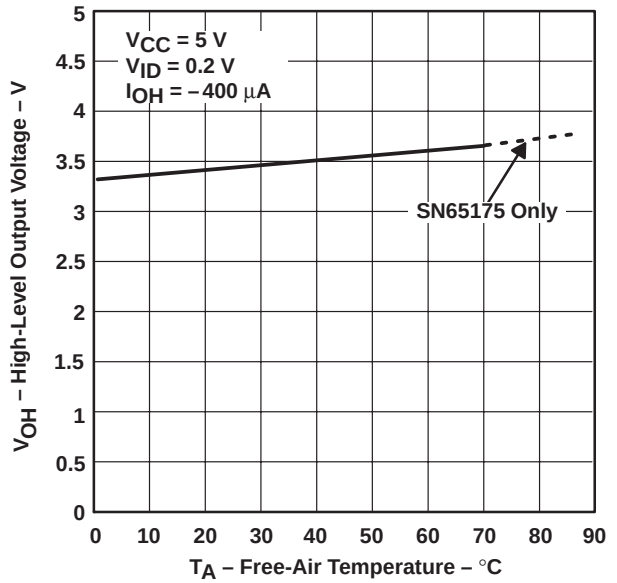


Figure 6

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

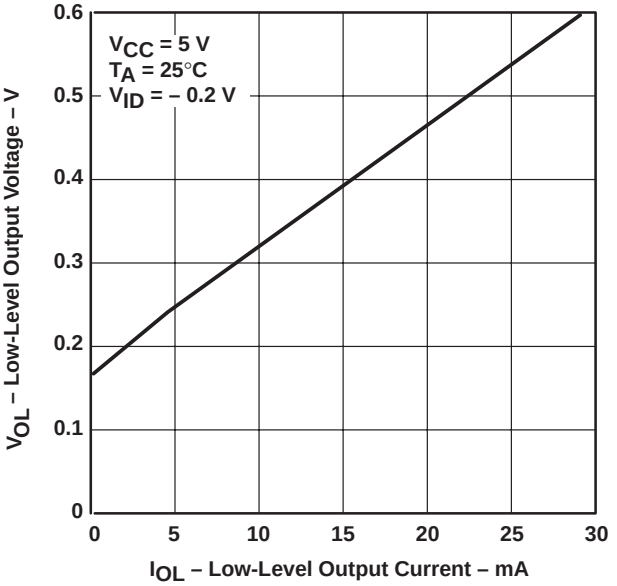


Figure 7

TYPICAL CHARACTERISTICS

LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

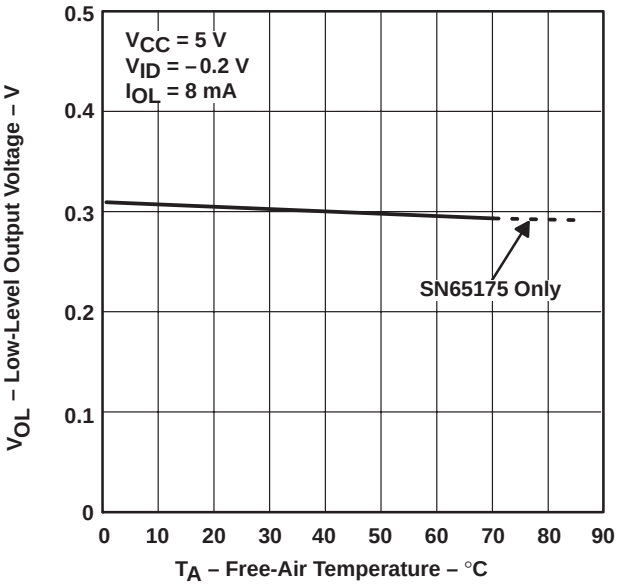


Figure 8

OUTPUT VOLTAGE vs ENABLE G VOLTAGE

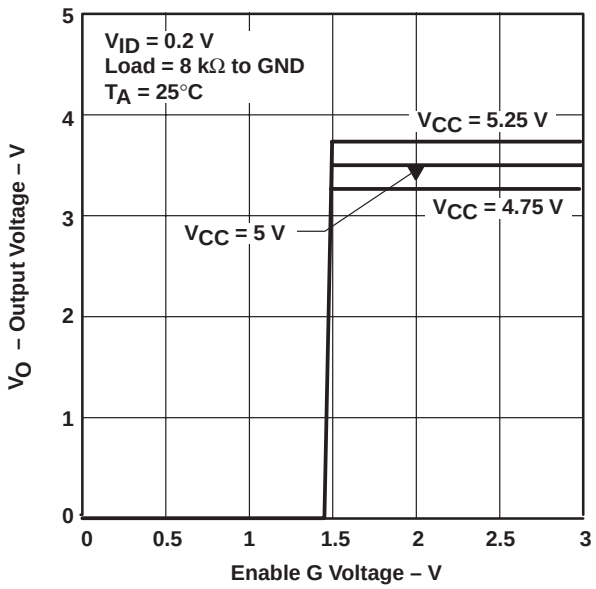


Figure 9

OUTPUT VOLTAGE vs ENABLE G VOLTAGE

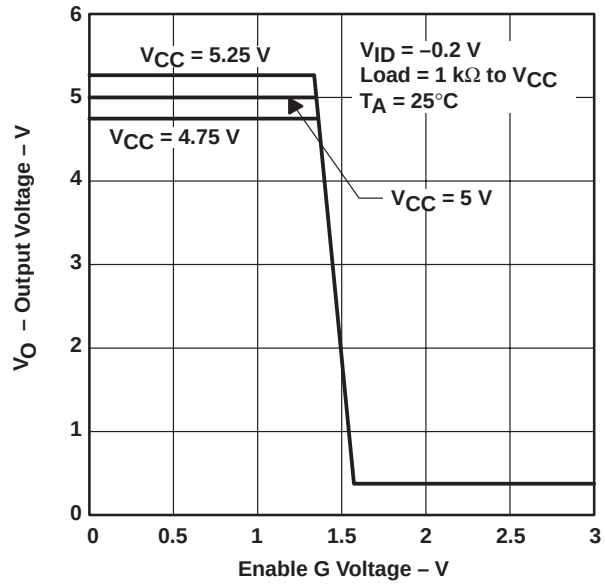


Figure 10

SUPPLY CURRENT (ALL RECEIVERS) vs SUPPLY VOLTAGE

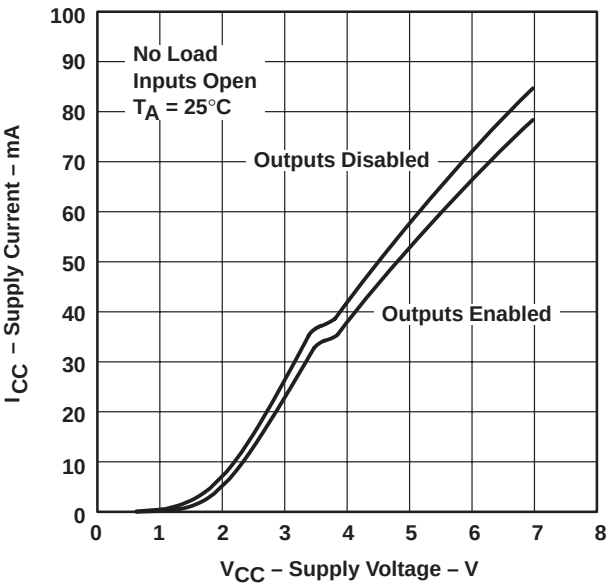


Figure 11

TYPICAL CHARACTERISTICS

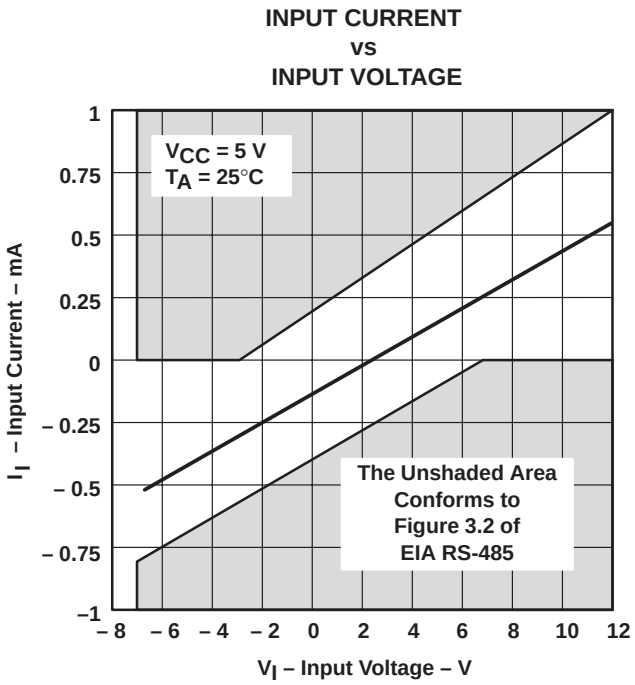
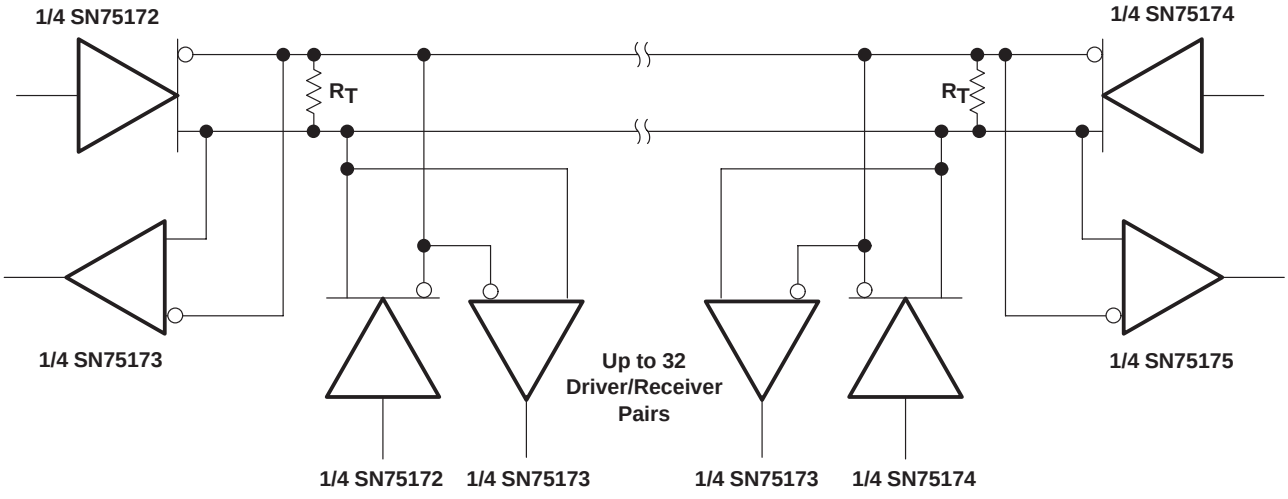


Figure 12

APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristicc impedance ($R_T = Z_O$). Stub lengths off the main line should be kept as short as possible.

Figure 13. Typical Application Circuit

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN65175D	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN65175DR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN75175D	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN75175DR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN75175J	OBSOLETE	CDIP	J	16		None	Call TI	Call TI
SN75175N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN75175NSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

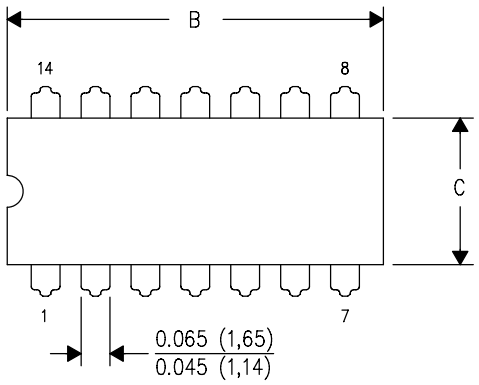
(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
None: Not yet available Lead (Pb-Free).
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

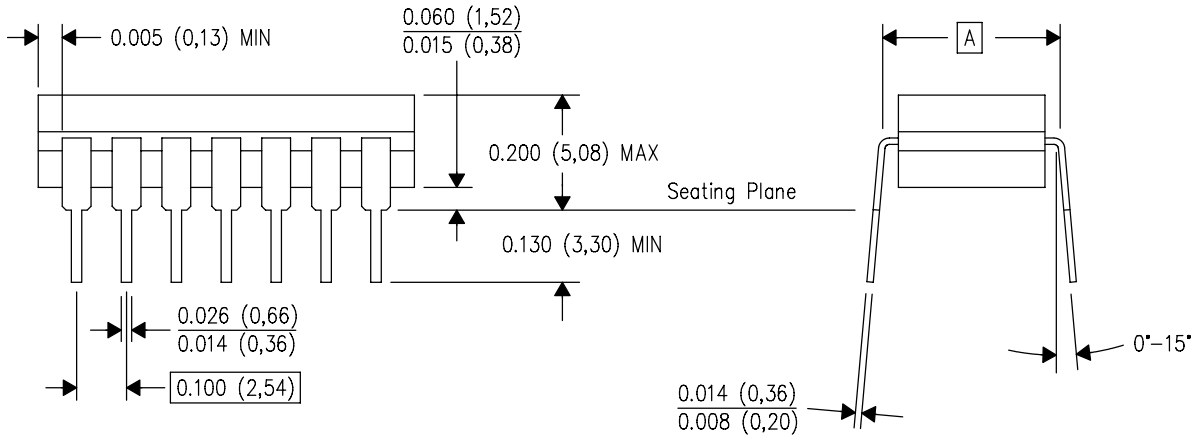
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



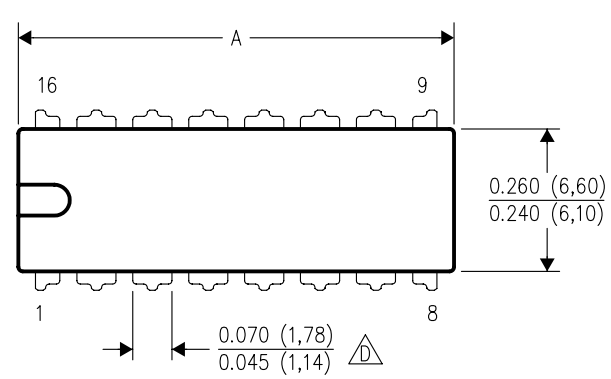
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

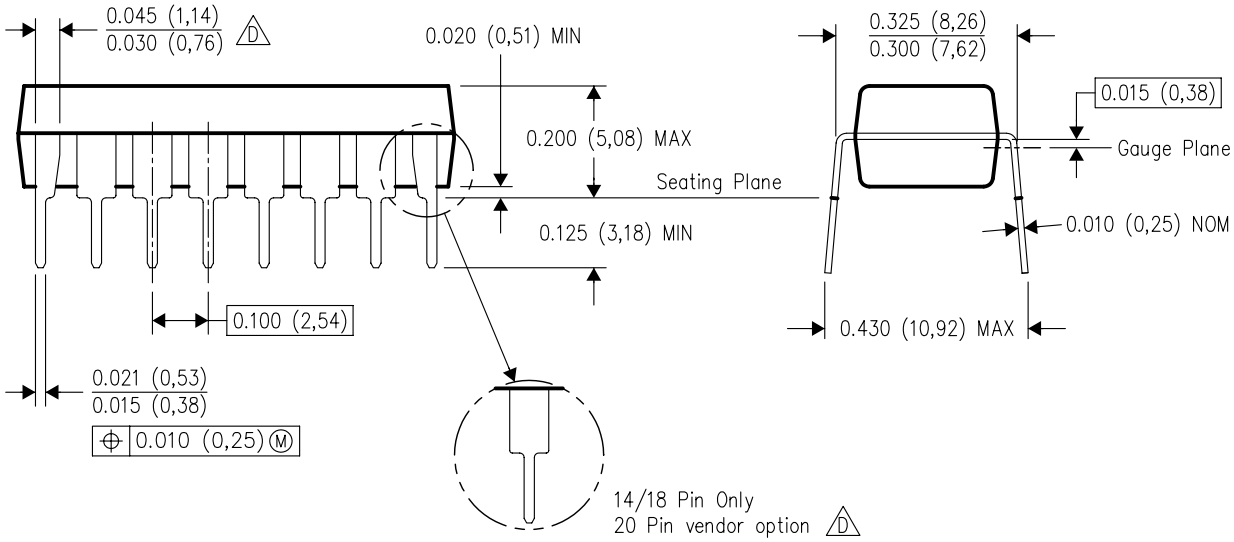
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



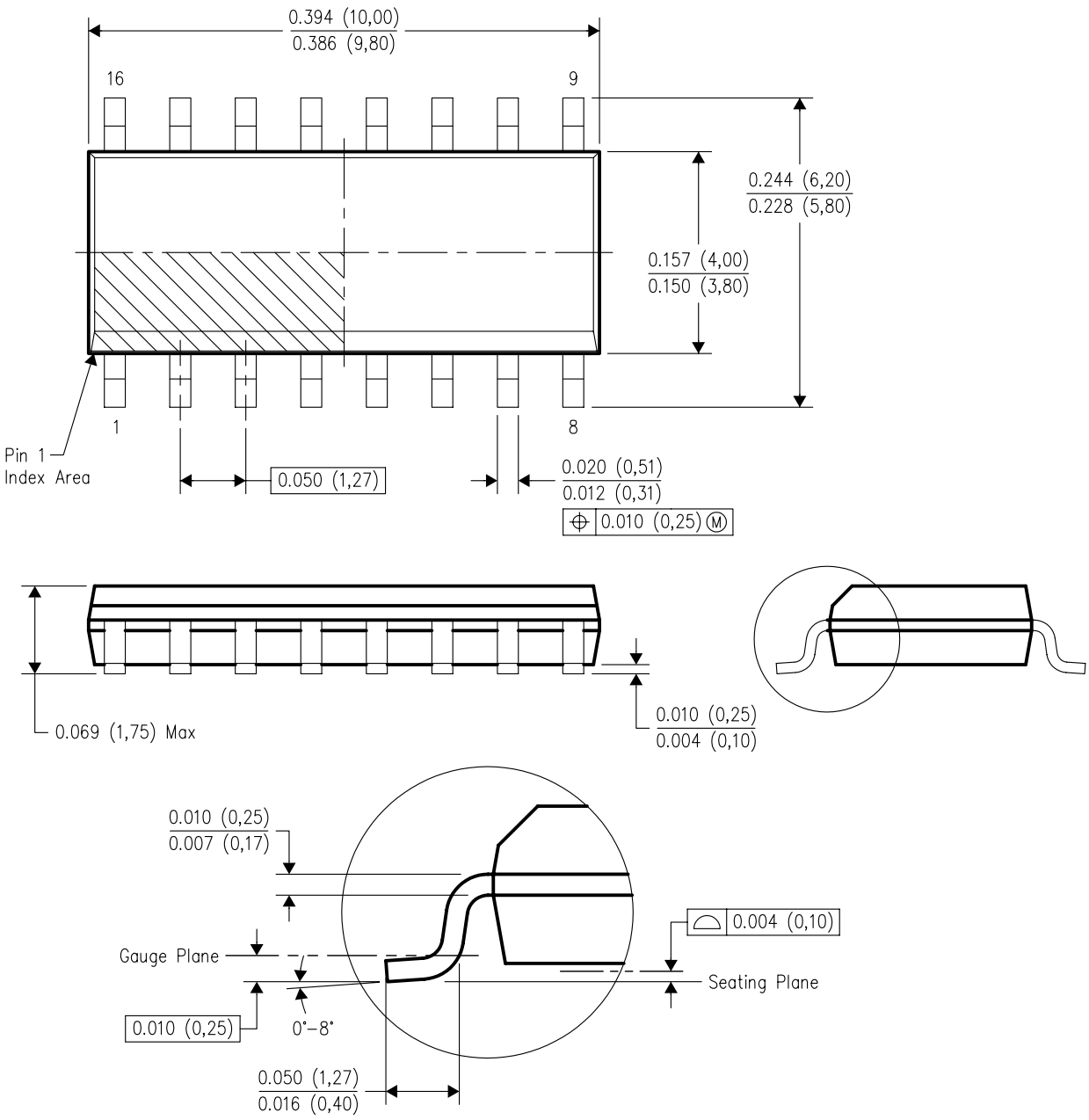
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL–OUTLINE PACKAGE

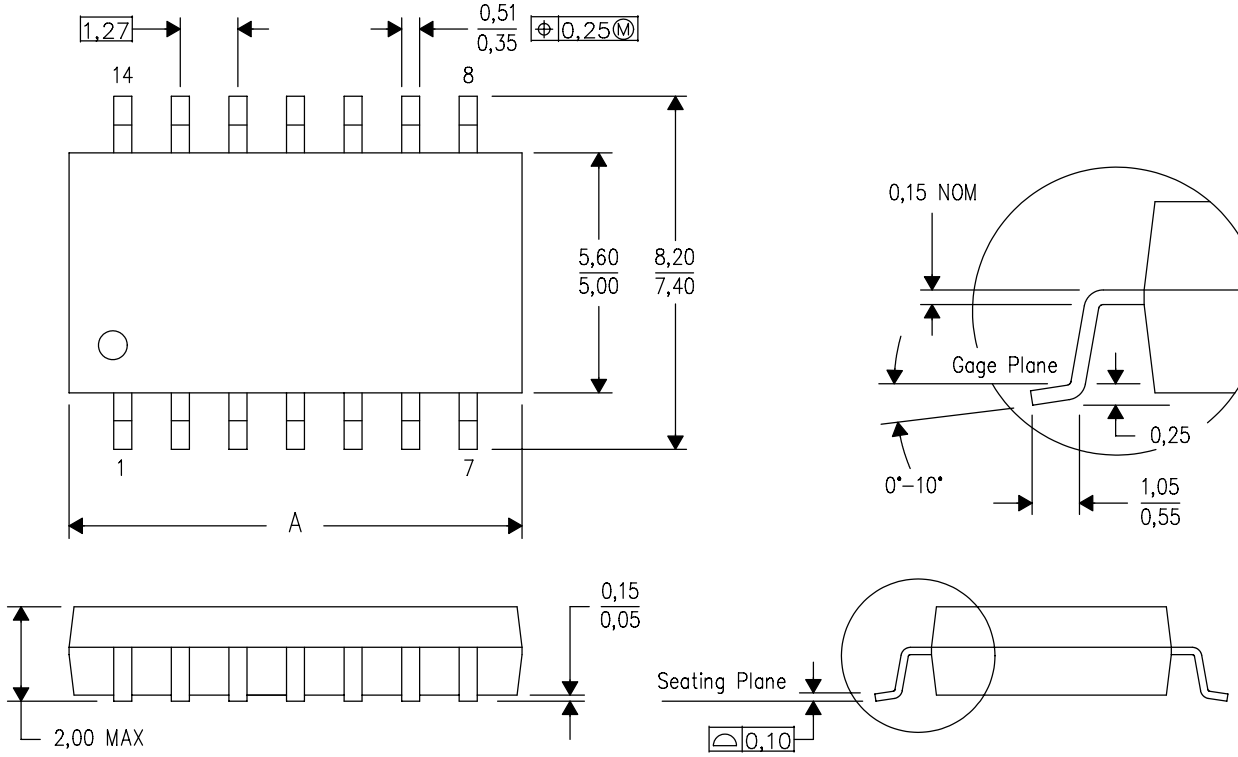


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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